

股票代號：2404

漢唐集成股份有限公司 法人說明會

United Integrated Services Co. Investor Conference

2025/06/19



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- 漢唐集成公司簡介 (About UIS)
- 營運概況說明 (Operation)
- 財務狀況說明 (Financials)
- 業務展望 (Future Prospects)
- Q & A

漢唐集成成立於1982年，為一以「全面性整合服務」方式，專業提供高科技產業建廠之系統集成服務公司；主要業務範圍包括高科技廠房各系統，包括電腦、控制、無塵室、機電、電信系統之施作與整合服務。

漢唐集成的工程系統完備，服務更講求以提供整體施作方式一次滿足客戶需求。針對高科技事業建廠所需之無塵室系統、機械系統、電氣系統、配管系統、製程支援系統、儀錶及控制系統、通訊系統、生命安全系統、門禁及安全管理系統、大宗及特殊氣體系統、超純水（UPW）及再生系統、超純水回收系統、廢水處理與製程化學品輸送，及二次配管路工程等系統，均囊括在漢唐集成的服務範圍內。

漢唐集成就以上各項系統提供從採購、施工、試車、移交、保固到維護保養的服務，過程中並實施深化業主需求、提高施工品質的服務，以科技方式整合以上各項系統工程，達成介面統一，使客戶完全無需擔憂各個不同系統之間的介面整合問題；漢唐集成是國內目前具備系統工程整合技術及能力且有實績有信譽的廠商，並獲得業主及業界多次的授獎及讚譽。

United Integrated Services Co., Ltd is a multidisciplinary engineering and construction company capable of overall systems coordination. We provide fully integrated design/build services to our clients in the high technology industry for their manufacturing facility needs.

Our scope of services includes high-tech factory construction, where clean-room systems, HVAC, electrical systems, instrumentation and control, process utilities, telecommunication systems, and tool hook-up are all vital components requiring total coordination.

UIS provides integrated services encompassing procurement, construction, testing, handover, warranty, and maintenance for all the aforementioned systems. Throughout the process, we deepen client requirements, enhance construction quality, and integrate these systems using technology, ensuring interface uniformity and eliminating concerns regarding integration issues between different systems.

In short, we strive to be a one-stop shop to satisfy our clients' every facility need. Our company is one of the few domestic firms with the technical expertise, capabilities, and achievements in system engineering integration, enjoying multiple awards and accolades from clients and the industry.

漢唐科技工程有
限公司成立
**Company
Established**

申請掛牌上市
(股票代號 2404)
IPO

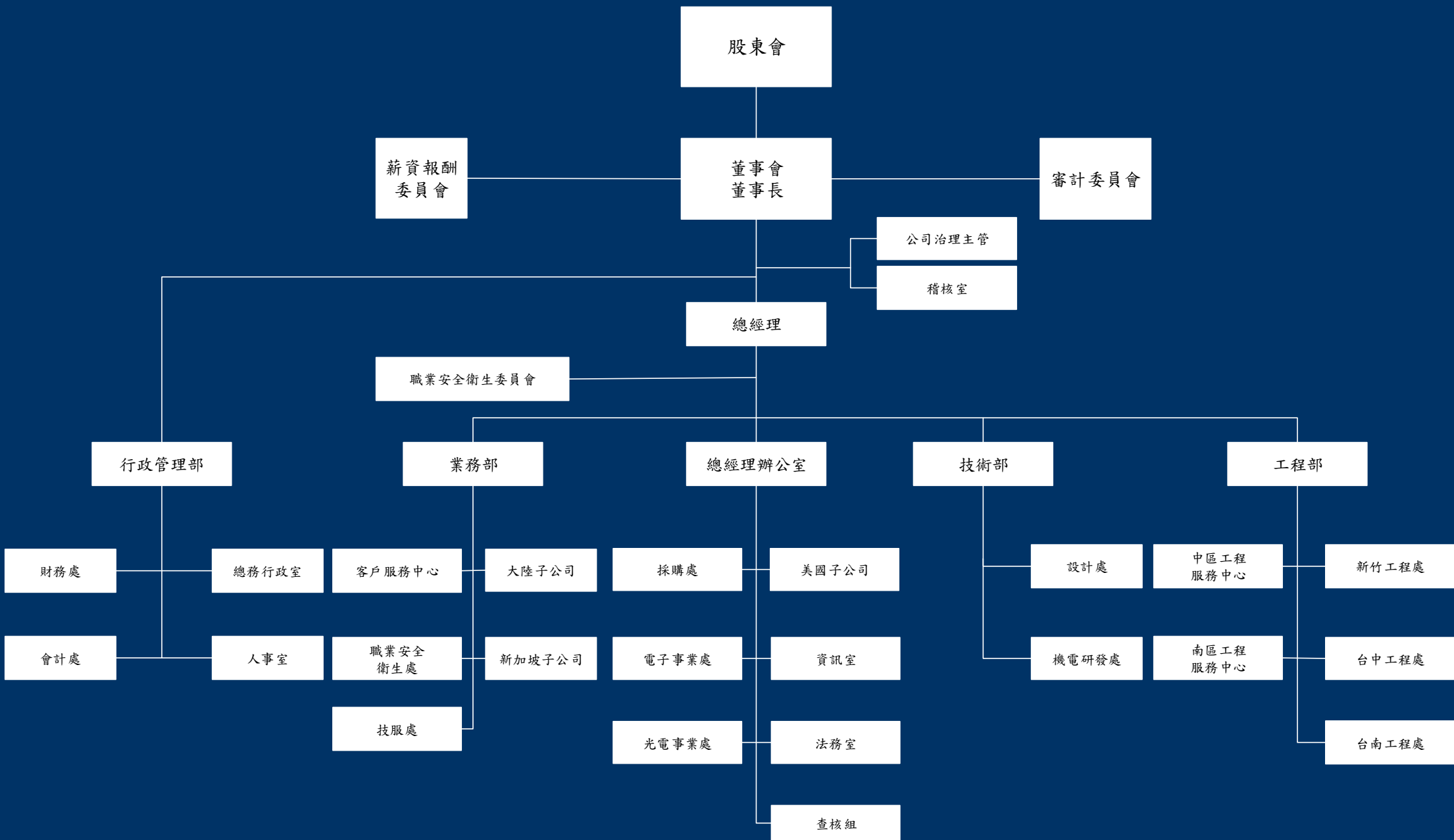
成立江西漢唐系統
集成有限公司
**Established UIS,
Jiang Xi**

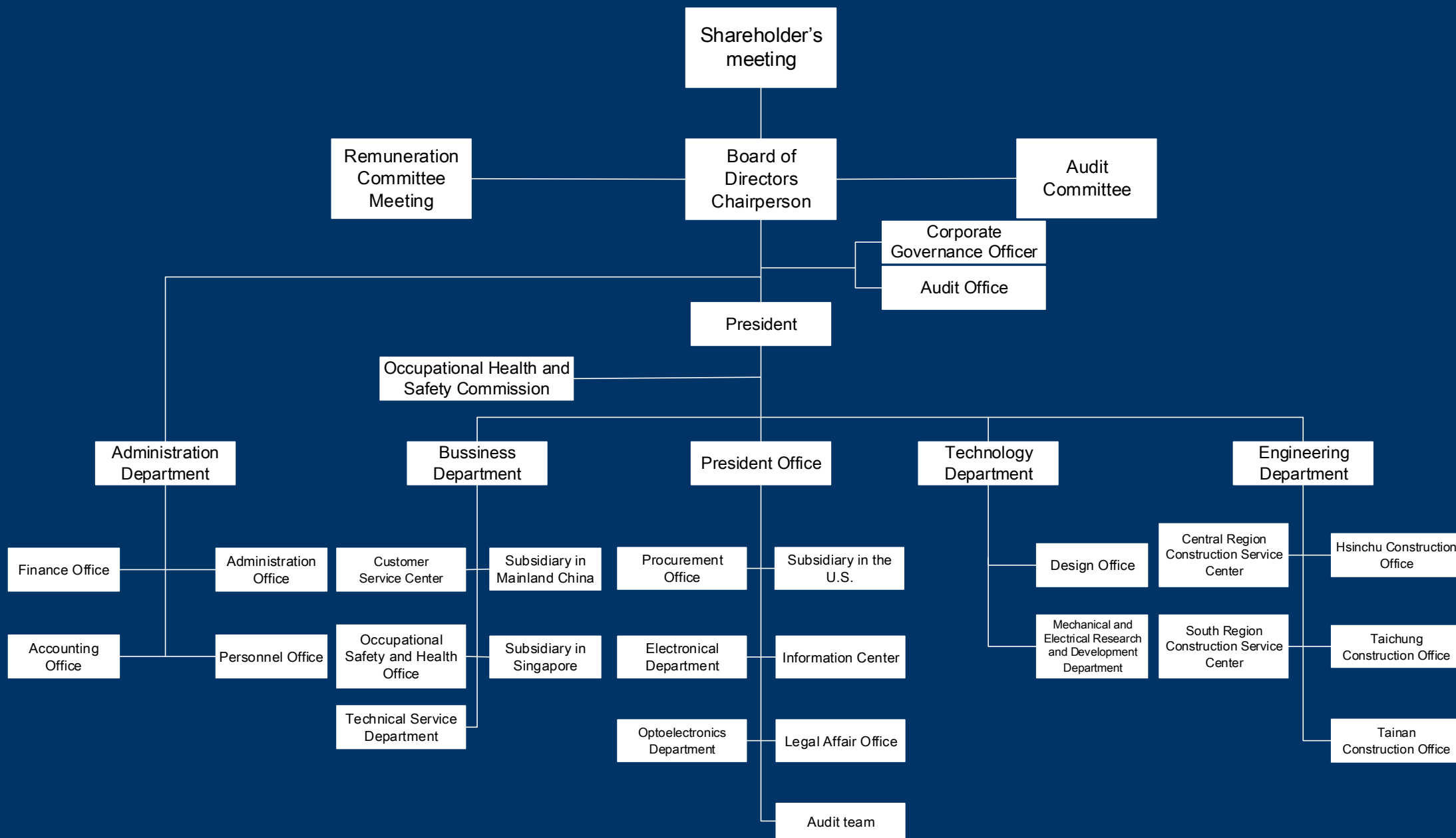
成立美國漢唐
集成公司
**Established
UIS USA**



UIS History 沿革

uis





UIS客戶群(UIS Clients)

★ Main office
Zhonghe

● Branch office and
Service Locations

Hsinchu
Taichung
Tainan
Shanghai
Nanjing
Hefei
Shenzhen
Singapore
Arizona

日本熊本 關鍵材料設備供應
● tsmc FAB 23



Hsinchu

- tsmc FAB 12 P5, P6,P7,P8
 - tsmc FAB 20 P1- P2
- ## Longtan
- QPM FAB C (TSMC BP03)

Taichung

- tsmc FAB 15 P1- P7
- Micron FAB A2,A3
- auo L8B FAB
- tsmc Solar
- Micron AATT (TCP2)
- tsmc AP5B

Chiayi

- tsmc AP7P1 MEP

Tainan

- tsmc FAB 14 P4- P7
- tsmc FAB 18 P1- P8
- tsmc AP8
- Micron Falcon A

Kaohsiung

- tsmc FAB 22 P1- P2

深圳

合肥

南京

上海

熊本

新加坡

Singapore

● VSMC P1 CR

■ 工程承包範圍

Scope of Engineering

- 無塵室工程
Cleanroom
- 機電工程
Mech. / Elec. Engineering
- 水氣化等特殊系統工程
UPW / WWT / Gas / Chem.
Systems
- 監控系統工程
I&C

■ 服務範圍

Scope of Services

- 工程施工
Construction
- 售後服務
After Sale Services

台灣積體電路製造股份有限公司

台積電三廠

台積電四廠

台積電六廠

台積電十二廠 P1, P2, P3, P4, P5, P6, P7, P8

台積電十四廠 P1, P2, P3, P4, P5, P6, P7

台積電十五廠 P1, P2, P3, P4, P5, P6, P7

台積電十八廠 P1, P2, P3, P4, P5, P6, P7, P8

台積電南京廠 F16P1 P2

台積電龍潭 BP03

台積電美國F21P1

台積電日本F23 (關鍵材料設備供應)

台積電二十廠 P1, P2

台積電二十二廠 P1, P2

台積電封測五廠 AP5B

台積電封測七廠 AP7A MEP

台積電封測八廠 AP8

華邦電子股份有限公司

華邦 FAB I , FAB II , FAB III , FAB IV

華邦 FAB CTSP, FAB 6C

旺宏電子股份有限公司

旺宏 FAB I , FAB II, FAB III

台灣美光記憶體股份有限公司

美光 FAB A1 A2 A3 A3M2a A3M2b

美光 AATT (TCP2)

美光 Falcon A

世界先進積體電路股份有限公司

VSMC P1 CR

力晶半導體股份有限公司

力晶 FAB 8A , P3 , P4, P5

Taiwan Semiconductor Manufacturing Company Ltd.

TSMC FAB III

TSMC FAB IV

TSMC FAB VI

TSMC FAB XII P1, P2, P3, P4, P5, P6, P7, P8

TSMC FAB XIV P1, P2, P3, P4, P5, P6, P7

TSMC FAB XV P1, P2, P3, P4, P5, P6, P7

TSMC FAB XVIII P1, P2, P3, P4, P5, P6, P7

TSMC China Nanjing F16 P1, P2

TSMC BP03

TSMC USA F21

TSMC F20 P1-P2

TSMC F22 P1-P2

TSMC AP5B

TSMC AP7A MEP

TSMC AP8

Winbond Electronics Corp

Winbond FAB I , FAB II , FAB III , FAB IV

Winbond FAB CTSP, FAB 6C

Macronix International Co., Ltd

MXIC FAB I , FAB II, FAB III

Micron Memory Taiwan Co., Ltd.

Micron FAB A1 A2 A3 TCP2 A3M2a A3M2b

Micron AATT (TCP2)

Micron Falcon A

VisionPower Semiconductor

Manufacturing Company Pte. Ltd.

VSMC P1 CR

Powerchip Technology Corporation

PSC FAB 8A , P3 , P4, P5



友達光電股份有限公司

- 友達 FAB L3C
- 友達 FAB L3D (QDI Line I)
- 友達 FAB L4A
- 友達 FAB L5A
- 友達 FAB L5B
- 友達 FAB L5C
- 友達 FAB L5D (QDI Line II)
- 友達 FAB L6A
- 友達 FAB L6B (QDI Line III)
- 友達 FAB L7A, L7B
- 友達 FAB L8A, L8B

奇美電子股份有限公司

- 奇美 FAB 三廠
- 奇美 FAB 四廠
- 奇美 FAB 五廠
- 奇美 FAB 六廠
- 奇美 FAB 七廠
- 奇美 FAB 八廠

高通液晶顯示器股份有限公司

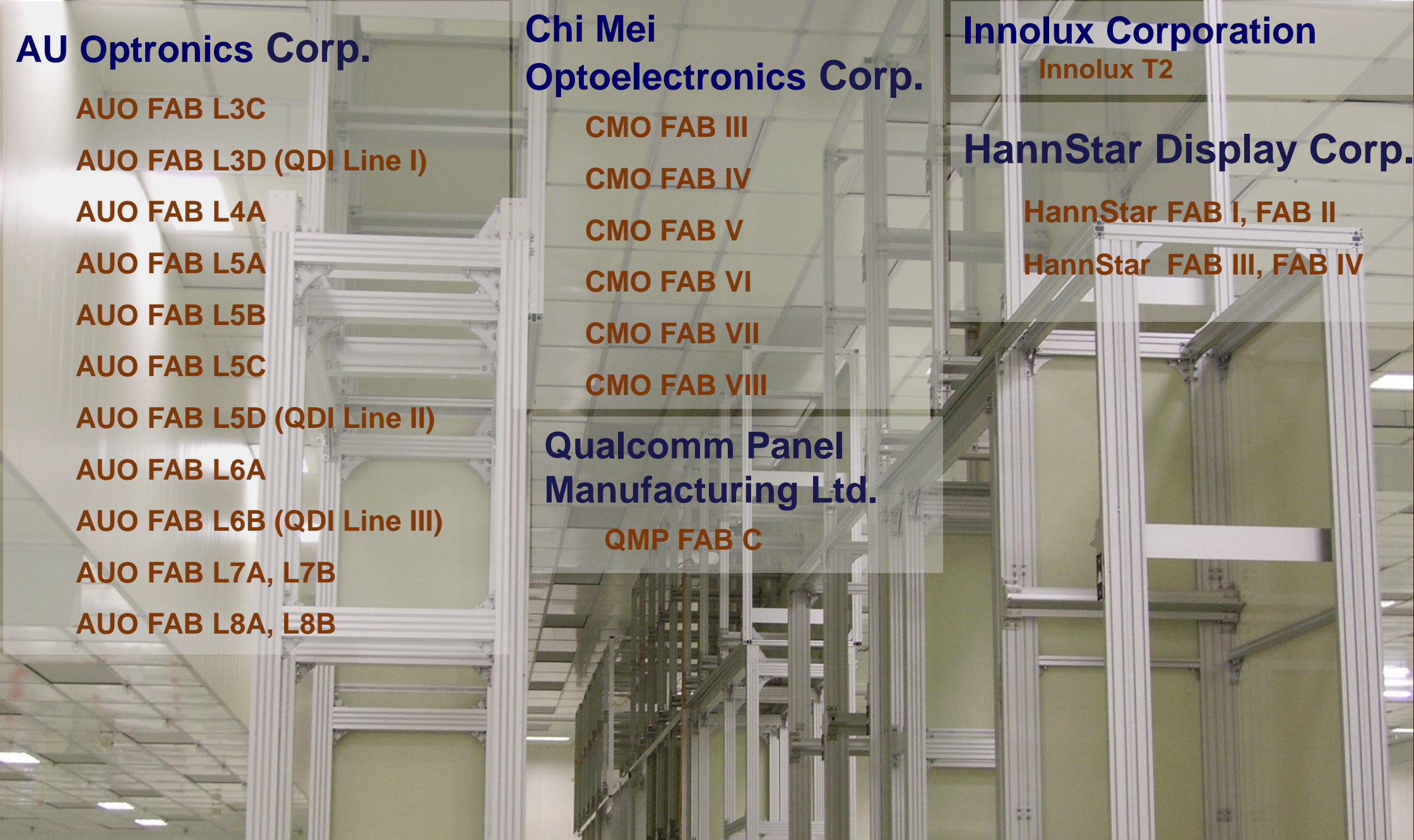
- 高通 FAB C

群創光電股份有限公司

- Innolux T2廠

瀚宇彩晶股份有限公司

- 瀚宇彩晶 FAB I, FAB II
- 瀚宇彩晶 FAB III, FAB IV



AU Optronics Corp.

- AUO FAB L3C
- AUO FAB L3D (QDI Line I)
- AUO FAB L4A
- AUO FAB L5A
- AUO FAB L5B
- AUO FAB L5C
- AUO FAB L5D (QDI Line II)
- AUO FAB L6A
- AUO FAB L6B (QDI Line III)
- AUO FAB L7A, L7B
- AUO FAB L8A, L8B

**Chi Mei
Optoelectronics Corp.**

- CMO FAB III
- CMO FAB IV
- CMO FAB V
- CMO FAB VI
- CMO FAB VII
- CMO FAB VIII

**Qualcomm Panel
Manufacturing Ltd.**

- QMP FAB C

Innolux Corporation
Innolux T2

HannStar Display Corp.

- HannStar FAB I, FAB II
- HannStar FAB III, FAB IV

近五年盈餘分配狀況

Income Statement

	109年 (2020)	110年 (2021)	111年 (2022)	112年 (2023)	113年 (2024)	114年Q1 (2025Q1)
營業收入(千元) Rev.(thousand)	35,836,642	25,606,141	48,200,310	68,889,680	47,421,600	11,517,514
毛利(千元) Gross Profit(thousnad)	5,684,146	4,086,636	6,718,724	7,531,191	8,512,585	2,673,076
毛利率 Gross Profit %	15.86%	15.96%	13.94%	10.93%	17.95%	23.21%
本期稅後損益(千元) EAT(thousand)	4,091,332	2,820,482	4,101,845	4,847,498	6,263,271	2,015,414
每股盈餘(元) EPS	21.16	14.53	21.25	24.82	32.94	10.55
現金股利(元) Cash Dividends	17.00	13.00	15.00	21.00	28.00	
股利發放率 Dividend Payout Ratio	80.34%	89.47%	70.59%	84.61%	85.00%	
負債佔資產比率 Debt Asset Ratio	62.47%	58.88%	68.30%	73.25%	67.96%	
流動比率 Current Ratio	140.70%	143.61%	132.50%	128.24%	138.62%	
純益率 Net Profit Margin	11.42%	11.01%	8.51%	7.04%	13.21%	

近五年營收 (Revenue)

Unit: NTD 100 million 單位：億元

■ 個體營收

Individual

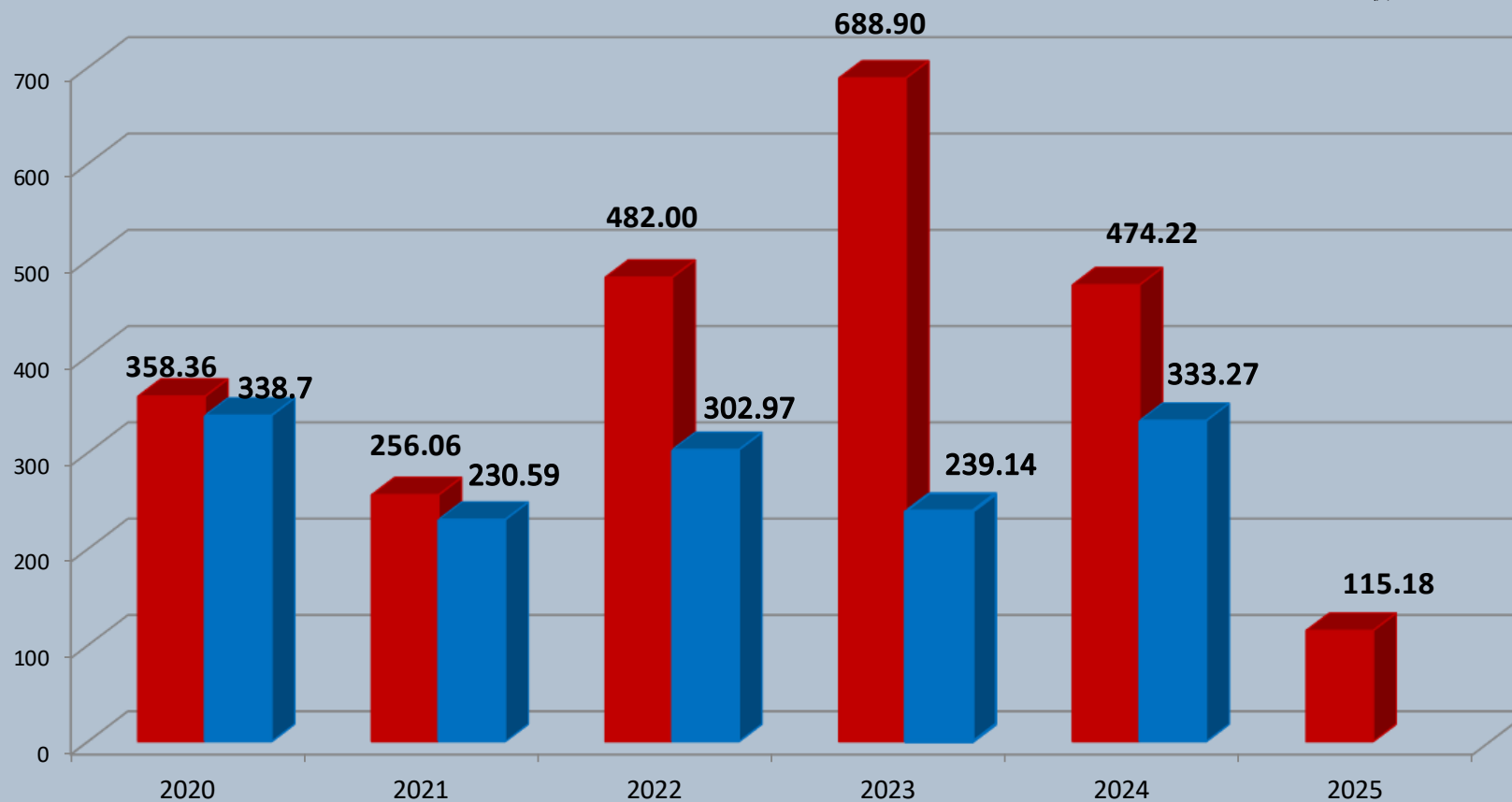
■ 合併營收

Consolidated

漢唐 2020 至 2025 Q1 營業收入

單位:億元

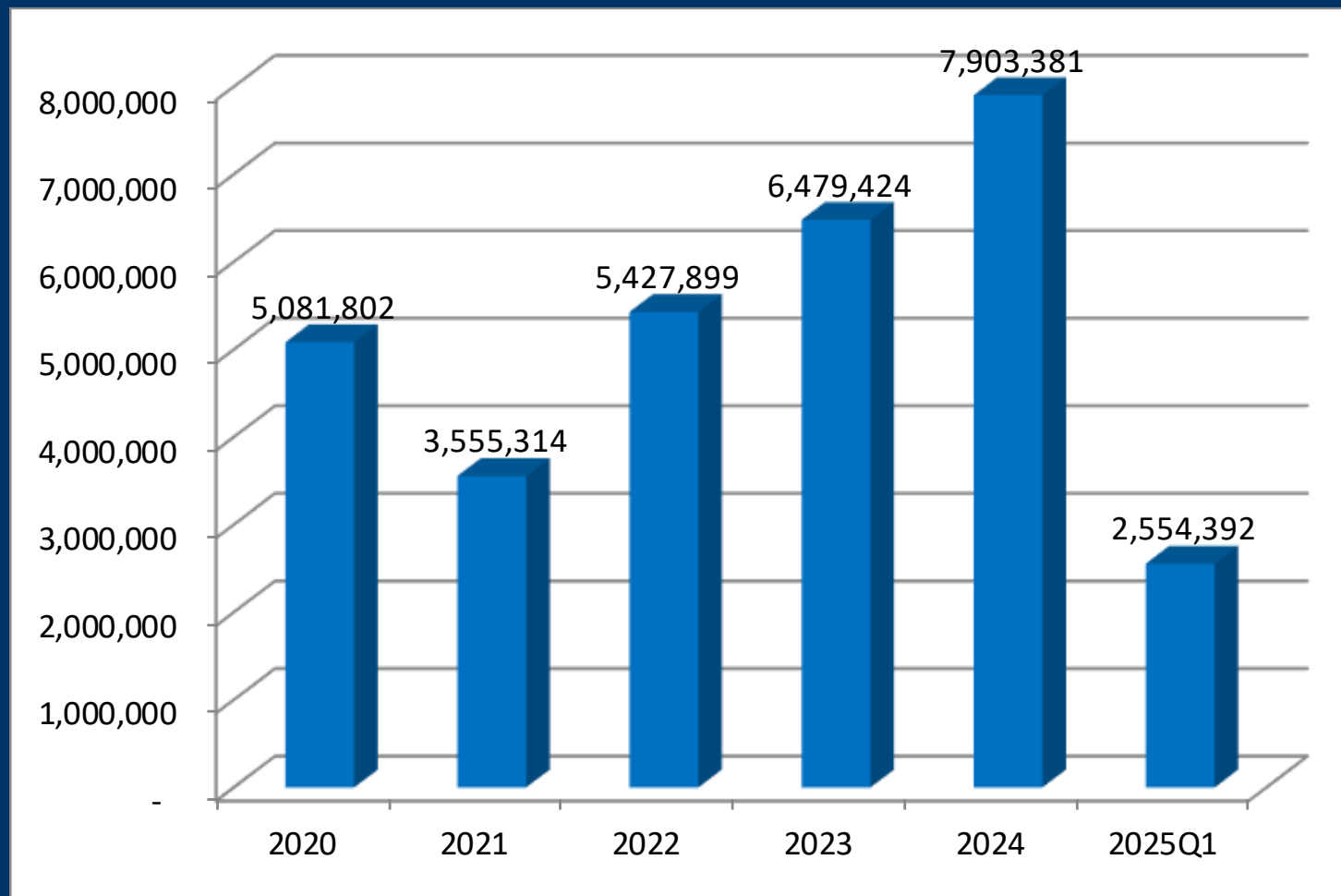
■ 合併營
收



稅前淨利 (EBIT)

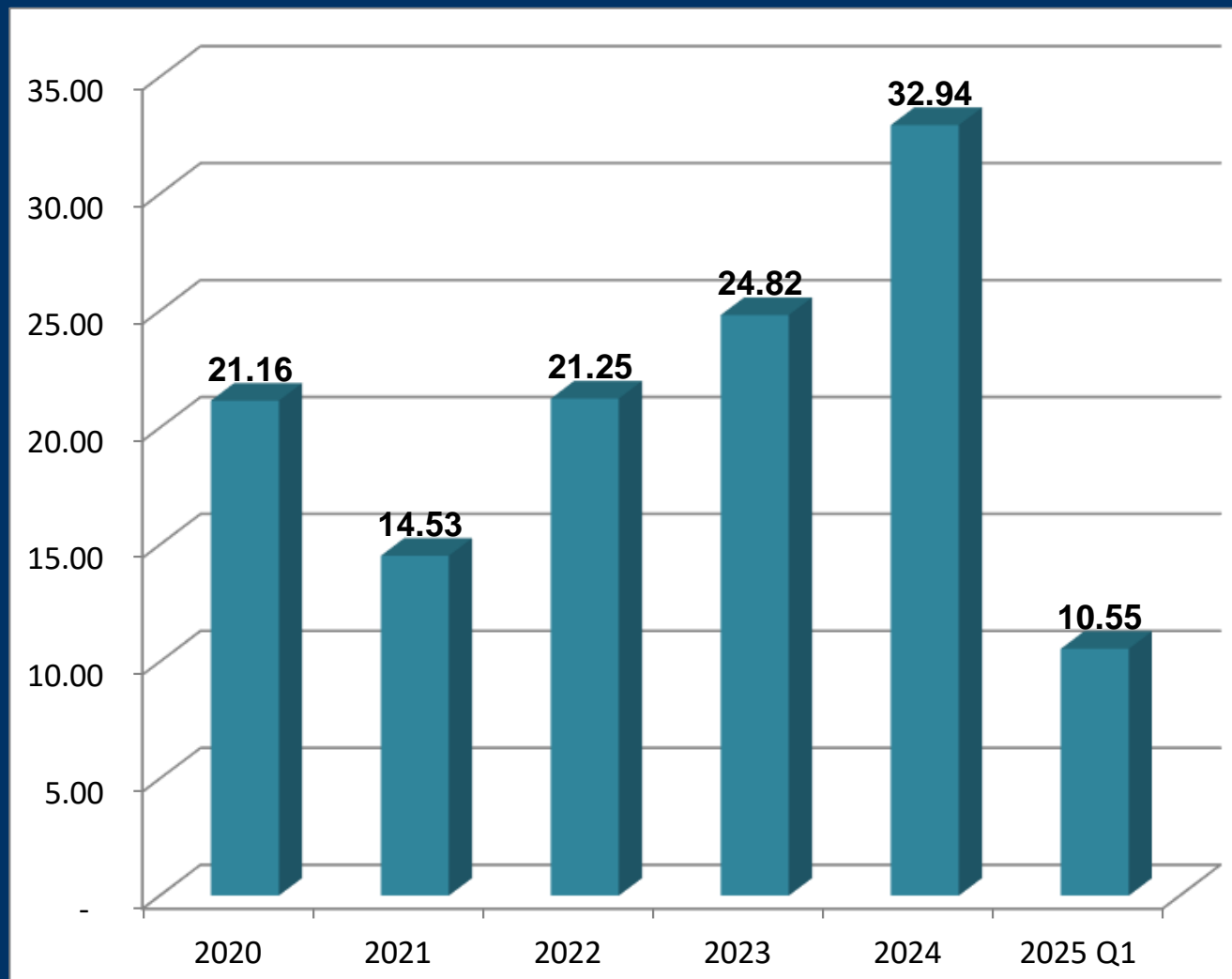
Unit: NTD thousand

單位：仟元



每股盈餘 (EPS)

Unit: NTD



累計接單狀況統計 Business in total

➤ 114年接單合約金額(1~05月份)

2025 Contract Value **NTD 83,676,500 仟元**

➤ 114年1月至05月累計營收

Accumulated Rev. **NTD 20,508,570 仟元**
(from Jan. to July)

➤ 截至114年05月已簽約未認列之金額

Accumulated **NTD 132,266,447 仟元**
Account Receivable
(to May)

114年Q1合併資產負債表

2025 Q1 Consolidated Balance Sheet

單位:仟元
Unit: thousand

	114/3/31	113/12/31	113/3/31		114/3/31	113/12/31	113/3/31
現金及約當現金 Cash	15,448,196	11,648,594	9,422,680	銀行借款 Bank loan	-	-	4,139,700
				應付帳款 PA	7,656,357	7,647,170	7,919,256
合約資產 Contract assets-current	5,868,615	4,885,744	16,616,768	合約負債 Contract liabilities	30,305,092	20,210,626	20,718,121
其他流動資產 Others	34,105,481	26,012,615	19,950,615	其他流動負債 Others	8,830,915	2,835,004	6,364,614
流動資產合計 Total Current Assets	55,422,292	42,546,953	45,990,063	流動負債合計 Total Current Liabilities	46,792,364	30,692,800	39,141,691
不動產、廠房及設備 PPE	1,349,148	1,344,382	1,366,877	其他非流動負債 Others	970,060	998,314	994,193
其他非流動資產 Others	2,623,064	2,740,496	2,661,437				
非流動資產合計 Total Non-current Assets	3,972,212	4,084,878	4,028,314	負債總計 Total Liabilities	47,762,424	31,691,114	40,135,884
				股東權益總計 Total SE	11,632,080	14,940,717	9,882,493
資產總計 Total Assests	59,394,504	46,631,831	50,018,377	負債及權益總計 Total Liabilities+SE	59,394,504	46,631,831	50,018,377

若本簡報引述的財務資料，與已對外公告的財務報告有不符的情形，以已對外公告的財務報告的內容為主。

If there is any conflict between, or any difference in the financial information quoted in this presentation and the announced financial report, the announced financial report shall prevail

財務狀況說明 Financials

uis

114年Q1及113年合併損益表 2025 Q1 & 2024 Consolidated Income Statement

單位:仟元
Unit: thousand

	114年1月至3月 2025 Jan.~Mar.		113年1月至3月 2024 Jan.~Mar.		113年1月至12月 2024 Jan.~Dec.		112年1月至12月 2023 Jan.~Dec.	
營業收入 Revenue	11,517,514	100%	12,253,850	100%	47,421,600	100%	68,889,680	100%
營業成本 Cost	8,844,438	77%	10,720,852	87%	38,909,015	82%	61,358,489	89%
營業毛利 Gross Profit	2,673,076	23%	1,532,998	13%	8,512,585	18%	7,513,191	11%
營業費用 Operating expenses	479,802	4%	342,538	3%	1,652,227	3%	1,469,682	2%
營業淨利 Operating Income	2,193,274	19%	1,190,460	10%	6,860,358	15%	6,061,509	9%
營業外收入淨額 Net non-operating income	361,118	3%	426,892	3%	1,043,023	2%	417,915	-
稅前淨利 EBIT	2,554,392	22%	1,617,352	13%	7,903,381	17%	6,479,424	9%
所得稅費用 Income Tax	538,978	5%	335,982	3%	1,640,110	4%	1,631,926	2%
本期淨利 Net Income	2,015,414	17%	1,281,370	10%	6,263,271	13%	4,847,498	7%
本期淨利歸屬於母公司 Net Income (Parent company)	1,989,414	17%	1,273,769	10%	6,190,440	13%	4,655,215	7%
綜合損益歸屬於母公司 Composite Net Income (Parent Company)	1,940,096	17%	1,379,833	11%	6,256,584	13%	4,528,791	7%
基本每股盈餘 EPS	10.55		6.79		32.94		24.82	
稀釋每股盈餘 Diluted EPS	10.49		6.75		32.60		24.48	

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財務狀況說明 Financials

uis

一一四年，漢唐預期將受惠於主要半導體客戶的建廠計畫與資本支出，推動業績成長。隨著AI技術持續驅動半導體產業發展，先進製程與先進封裝需求進一步提升，漢唐將深入參與二奈米廠建置，並加大投入CoWoS先進封裝廠建造，以強化技術優勢與市場競爭力。此外，隨著北美地區重要專案二期工程的啟動，關鍵客戶進一步加大與加速其海外工廠的擴建，公司將在當地取得之豐富建廠經驗和客戶高度信任的基礎上，擴大海外工程服務位階和工程承攬範疇，深化全球市場布局。

記憶體市場方面，AI伺服器需求推動DRAM與高頻寬記憶體（HBM）市場成長，北美記憶體大廠的建廠與擴廠計畫預期將擴及後段製程，漢唐將與其緊密配合，確保競爭優勢與市場佔有率。

展望一一四年，全球市場仍受國際經濟環境與地緣政治影響，公司將靈活應對各國政策變動，調整營運策略，以確保穩健發展。綜合市場趨勢與專案進度，營收預期保持穩定，並將積極拓展新機會，推動長期成長。

In 2025, UIS is expected to benefit from the construction plans and capital expenditures of major semiconductor clients, driving business growth. As AI technology continues to propel the development of the semiconductor industry, demand for advanced nodes and advanced packaging continues to rise. UIS will be deeply involved in the construction of 2nm fabs and will further invest in CoWoS advanced packaging facilities to strengthen its technological edge and market competitiveness.

In addition, with the launch of Phase II of a key project in North America, the client is accelerating the expansion of its overseas manufacturing site. Building on its extensive construction experience and strong client trust in the region, UIS will expand the scope and positioning of its overseas engineering services, further deepening its global footprint.

In the memory sector, demand from AI servers is driving growth in DRAM and HBM. The fab construction and expansion plan of a major memory client is expected to extend into backend processes, and UIS will work closely with the client to maintain its competitive edge and market share.

Looking ahead to 2025, although the global market will continue to face challenges from macroeconomic conditions and geopolitical uncertainties, UIS will respond flexibly to policy changes across different regions and adjust its business strategies to ensure stable development. Based on current market trends and project progress, revenue is expected to remain steady, and the company will actively explore new opportunities to drive long-term growth.

Thank You

Q & A